

ThinFlex Corporation

No. 8, Luke 2nd.Rd., Luzhu Dist., Kaohsiung City, 821, Taiwan, R.O.C.
(Kaohsiung Science Park)
Tel: +886-7-6955236 Fax: +886-7-6955539
http://www.thinflex.com.tw
e-mail: service@thinflex.com.tw

ThinFlex H-1003ES Adhesiveless Copper Clad Laminate

(Halogen Free)

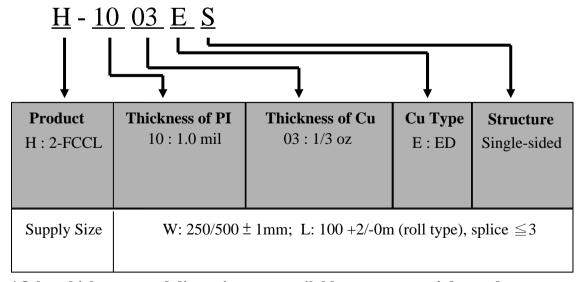
IPC Designation IPC-4204/11

ThinFlex H-1003ES is an adhesiveless metal clad polyimide film, furnished in the form of roll laminate with ED copper on one side. ThinFlex H-1003ES adhesiveless composites are designed for a wide variety of flexible circuit applications which require advanced material performance, temperature resistance, fine pitch, and high reliability.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Finer line etching capability
- * Low moisture absorption
- * Excellent flammability (Flame class UL 94V-0; UL File No. E219724)
- * Excellent chemical resistance
- * Excellent thermal, mechanical, and electrical properties

2. Specifications:



^{*}Other thicknesses and dimensions are available on customers' demand.

Technical Data Sheet: 201201





ThinFlex Corporation

e-mail: service@thinflex.com.tw

No. 8, Luke 2nd.Rd., Luzhu Dist., Kaohsiung City, 821, Taiwan, R.O.C.
(Kaohsiung Science Park)
Tel: +886-7-6955236 Fax: +886-7-6955539
http://www.thinflex.com.tw

3. Construction:

Copper foil

Polyimide film

4. Properties:

IPC Designation IPC-4204/11

Test item		Unit	H-1003ES	Test Method
Peel Strength				
As Received		Kgf/cm	≧0.9	IPC-TM650 2.4.9 B
Solder Float		Kgf/cm	≥0.9	IPC-TM650 2.4.13 B
After Temp. Cycling		Kgf/cm	≧0.9	IPC-TM650 2.4.9
Chemical Resistance		Kgf/cm	≧0.9	IPC-TM650 2.3.2
Tensile Strength (Base Film)		Kg/mm ²	26	IPC-TM-650 2.4.19
Elongation (Base Film)		%	30	IPC-TM-650 2.4.19
Tensile Modulus (Base Film)		Kg/mm²	510	ASTM D882
Initial Tear Strength (Base Film)		g	680	IPC-TM-650 2.4.16
Propagation Tear Strength (Base Film)		g	16	IPC-TM-650 2.4.17.1
Flexural Endurance, MIT				
M.D.		Cycles	≧500	JIS-C 6471, 0.8mmR, 0.5kg
T.D.		Cycles	≧500	JIS-C 6471, 0.8mmR, 0.5kg
Electrical Properties				
Surface Resistance		Ω	~10 ¹¹	IPC-TM650 2.5.17
Volume Resistance		Ω -cm	~1012	IPC-TM650 2.5.17
Insulation Resistance		Ω	~109	IPC-TM650 2.6.3.2
Dielectric Strength		kV/mil	6.0	ASTM-D149
Dielectric Constant		-	3.6	IPC-TM650 2.5.5.3
Dissipation factor		-	0.01	IPC-TM650 2.5.5.3
Physical and Thermal Pro	perties			
Dimensional Stability	M.D.	%	-0.1~0.1	IPC-TM650 2.2.4C
	T.D.	%	-0.1~0.1	IPC-TM650 2.2.4C
CTE		ppm/°C	26	ThinFlex
T _g	40	$^{\circ}\!\mathbb{C}$	327	ThinFlex
Solder Float	10sec at 288°C (550°F)	-	Pass	IPC-TM650 2.4.13
Moisture Absorption Test		%	1.1	IPC-TM650 2.6.2
Chemical Resistance- single		-	Pass	IPC-TM650 2.3.2
Thickness tolerance		um	37±10%	ThinFlex
UL Flame Class		-	94V-0	UL

^{*} Above data are typical values, and are not guaranteed values.

Technical Data Sheet: 201201



ThinFlex Corporation

No. 8, Luke 2nd.Rd., Luzhu Dist., Kaohsiung City, 821, Taiwan, R.O.C.
(Kaohsiung Science Park)
Tel: +886-7-6955236 Fax: +886-7-6955539
http://www.thinflex.com.tw
e-mail: service@thinflex.com.tw

5. Storage:

ThinFlex-H-1003ES will meet its shelf-life for at least 12 months after arrival at the user's factory when stored in the original packaging at temperatures of below 25°C and below 70% humidity. The products do not need refrigeration and should not be frozen.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

ThinFlex Corporation

No.8, Luke 2nd Rd., Luzhu Dist., Kaohsiung City 821, Taiwan, R.O.C. (Kaohsiung Science Park)

Tel: +886-7-6955236 Fax: +886-7-6955539

http://www.thinflex.com.tw e-mail: service@thinflex.com.tw

Technical Data Sheet: 201201